



# SOT1226-2

plastic thermal enhanced extremely thin small outline  
package; no leads; 5 terminals

15 August 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	X2SON5
<b>Package type industry code</b>	X2SON5
<b>Package style descriptive code</b>	HXSON (thermal enhanced extremely thin small outline; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	5-4-2012

Table 1. Package summary

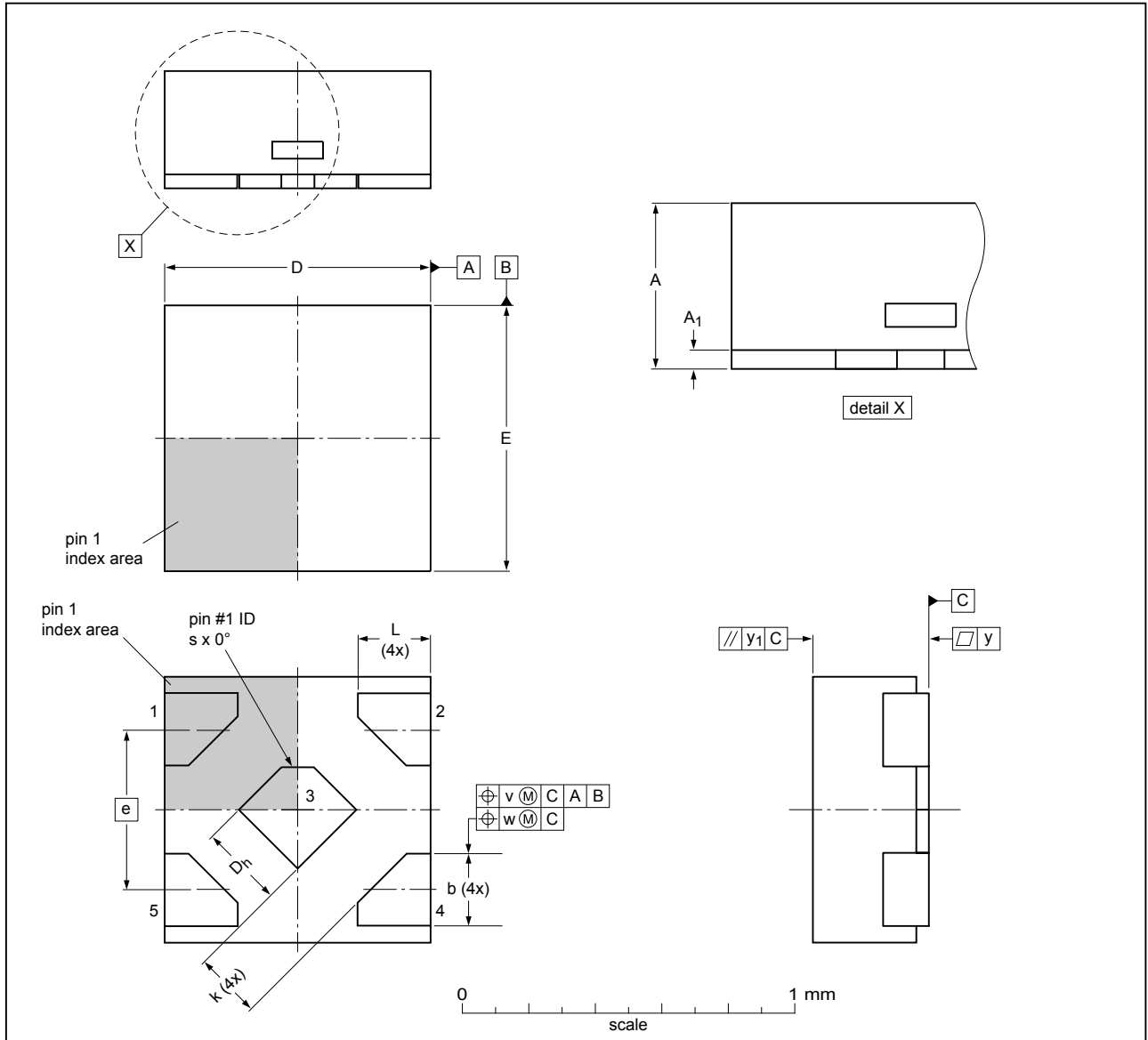
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.75	-	0.8	0.85	mm
E	package width	0.75	-	0.8	0.85	mm
A	seated height	0.3	-	0.32	0.35	mm
e	nominal pitch	-	-	0.48	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	5	-	



## 2. Package outline

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 x 0.8 x 0.32 mm

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Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	D	D <sub>h</sub>	E	b	e	K	L	s	v	w	y	y <sub>1</sub>
max	0.35	0.04	0.85	0.30	0.85	0.27			0.27					
mm nom	0.32	0.02	0.80	0.25	0.80	0.22	0.48		0.22	0.1	0.1	0.05	0.05	0.05
min	0.30	0.00	0.75	0.20	0.75	0.17		0.20	0.17	(ref)				

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Outline version	References			European projection	Issue date
	IEC	JEDEC	EIAJ		
SOT1226-2		---			-16-03-31- 16-04-05

Fig. 1. Package outline X2SON5 (SOT1226-2)

### 3. Legal information

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Date of release: 15 August 2016

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